

Form PTO-1449 (Rev. 8-83)		U.S. Department of Commerce						Atty. Docket No. D-21,389				Serial No.				
Information Disclosure Citation  (Use several sheets if necessary)										Applicants Belov et al.						
										Filing Date						
U.S. PATENT DOCUMENTS																
Examiner Initial		Document Number							Date	Name	Class	Subclass	Filing Date if Appropriate			
AD		6	4	3	6	8	3	5	8/2002	Kido et al.	438	693				
		6	4	4	3	8	1	1	9/2002	Nojo et al.	451	41				
		6	4	7	1	7	3	5	10/2002	Misra et al.	51	308				
		0	1	4	2	6	0	0	10/2002	Jacquinet et al.*	438	690				
		0	1	9	5	4	2	1	12/2002	Srinivasan et al.*	216	38				
		0	0	0	6	3	9	7	1/2003	Srinivasan et al.*	252	79.1				
AD		6	5	4	4	8	9	2	4/2003	Srinivasan et al.	438	692				
		0	1	7	1	0	7	2	9/2003	Ward et al.*	451	28				
FOREIGN PATENT DOCUMENTS																
		Document Number							Date	Country	Class	Subclass	Translation Yes    No			
AD		8	4	6	7	4	0	6/1988	EP	-	-					
Other Documents (including Author, Title, Date, Pertinent Pages, Etc.)																
AD		Zhao et al, "Direct CMP for STT", Semiconductor International (2001) pp. 145-150														
		Bonner et al, "Improved Direct Polish STI CMP Process with High Selectivity Slurry:Reduced Microscratching & Increased Productivity", Proceedings of 2002 CMP-MIC, pp 247-254														
		Garliardi et al, "Fixed Abrasives and Selective Chemistries:Some Real Advantages for Direct STI CMP", Proceedings of 2002 CMP-MIC, pp 288-290														
		Tseng et al., "STI CMP Process with High - Selectivity Slurry", Proceedings of 2002 CMP-MIC, pp. 255-259														
AD		Leduc et al, "CMP:Aiming for Perfect Planarization", Proceedings of 2002 CMP-MIC, pp 239-246														
		Devriendt et al, "Challenges for the Integration of Shallow Trench Isolation", Proceedings of 2003 CMP-MIC, pp 492-500														
EXAMINER: Anthony Opini								Date Considered 2/7/05								
* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in																

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<b>U.S. PATENT DOCUMENTS</b>															
Examiner Initial		Document Number							Date	Name	Class	Subclass	Filing Date if Appropriate		
AD		4	5	2	5	6	3	1	6/1985	Allison	290	4			
		5	6	7	1	8	5	1	9/1997	Johnson et al.	211	51			
		5	7	3	8	8	0	0	4/1998	Hosali et al.	216	99			
		5	7	5	9	9	1	7	6/1998	Grover et al.	438	690			
		6	0	1	9	8	0	6	2/2000	Sees et al.	51	308			
		6	0	4	2	7	4	1	3/2000	Hosali et al.	252	79.1			
		6	1	1	4	2	4	9	9/2000	Canaperi et al.	438	692			
		6	1	3	2	6	3	7	10/2000	Hosali et al.	252	79.1			
		6	2	1	8	3	0	5	4/2001	Hosali et al.	438	691			
		6	2	3	8	4	9	4	5/2001	Segal	148	421			
AD		6	4	1	0	4	4	4	6/2002	Kido et al.	438	693			
<b>FOREIGN PATENT DOCUMENTS</b>															
		Document Number							Date	Country	Class	Subclass	Translation Yes No		
<b>Other Documents (including Author, Title, Date, Pertinent Pages, Etc.)</b>															
AD		Cook, "Chemical Processes in Glass Polishing", Journal of Non-Crystalline Solids (1990) pp 152-171													
		Lo et al, "Characterization of Selective-CMP, Dummy Pattern and Reverse Mask Approaches in STI Planarization Process", Proceedings of 1999 CMP-MIC, pp-333-335													
		Lee et al., "The Effects of Slurries with Pattern Size and Step Height in Shallow Trench Isolation Chemical Mechanical Polishing", Proceedings of 2000 CMP-MIC, pp 288-290													
		Jin et al., "Advanced Front End CMP and Integration Solutions", Proceedings of 2000 CMP-MIC, pp 119-129													
		Bonner et al., "Development of a Direct Polish Process for Shallow Trench Isolation Modules", Proceedings of 2001 CMP-MIC, pp. 572-579													
AD		Xiao, "Introduction to Semiconductor Manufacturing Technology", Prentice-Hall Inc. (2001) pp. 384													
Examiner		Anthony Ajini							Date Considered					2/7/05	
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